# IGBT – Hybrid, Field Stop, Trench

## 650 V, 75 A, TO247

## AFGHL75T65SQDC

Using the novel field stop 4th generation IGBT technology and the 1.5th generation SiC Schottky Diode technology, AFGHL75T65SQDC offers the optimum performance with both low conduction and switching losses for high efficiency operations in various applications, especially totem pole bridgeless PFC and Inverter.

#### Features

- Maximum Junction Temperature:  $T_J = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(Sat)} = 1.6 V (Typ.) @ I_C = 75 A$
- 100% of the Parts are Tested for I<sub>LM</sub> (Note 2)
- Fast Switching
- Tight Parameter Distribution
- No Reverse Recovery/No Forward Recovery
- AEC–Q101 Qualified and PPAP Capable

#### **Typical Applications**

- Automotive
- On & Off Board Chargers
- DC-DC Converters
- PFC
- Industrial Inverter

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-to-Emitter Voltage	V <sub>CES</sub>	650	V
Gate-to-Emitter Voltage Transient Gate-to-Emitter Voltage	V <sub>GES</sub>	±20 ±30	V
$ \begin{array}{c} \mbox{Collector Current (Note 1)} & @\ T_C = 25^\circ C \\ & @\ T_C = 100^\circ C \end{array} $	Ι <sub>C</sub>	80 75	A
Pulsed Collector Current (Note 2)	I <sub>LM</sub>	300	А
Pulsed Collector Current (Note 3)	I <sub>CM</sub>	300	А
Diode Forward Current (Note 1)	lF	35 20	A
Pulsed Diode Maximum Forward Current	I <sub>FM</sub>	200	А
$ \begin{array}{ll} \mbox{Maximum Power Dissipation} & @\ T_C = 25^\circ C \\ & @\ T_C = 100^\circ C \end{array} $	P <sub>D</sub>	375 188	W
Operating Junction / Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	–55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 10 seconds	ΤL	265	°C

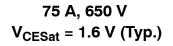
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

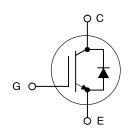
- 1. Value limited by bond wire
- 2. V<sub>CC</sub> = 400 V, V<sub>GE</sub> = 15 V, I<sub>C</sub> = 300 A, R<sub>G</sub> = 15  $\Omega$ , Inductive Load, 100% of the Parts are Tested.
- 3. Repetitive Rating: pulse width limited by max. Junction temperature



## **ON Semiconductor®**

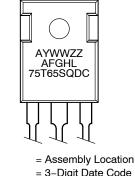
www.onsemi.com







### MARKING DIAGRAM



= 3-Digit Date Code
- 2 Digit Lot Traccability C

ZZ = 2-Digit Lot Traceability Code AFGHL75T65SQDC = Specific Device Code

Α

YWW

#### ORDERING INFORMATION

Device	Package	Shipping
AFGHL75T65SQDC	TO-247-3L	30 Units / Rail

#### THERMAL CHARACTERISTICS

Rating	Symbol	Мах	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ extsf{ heta}JC}$	0.4	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ extsf{ heta}JC}$	1.55	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

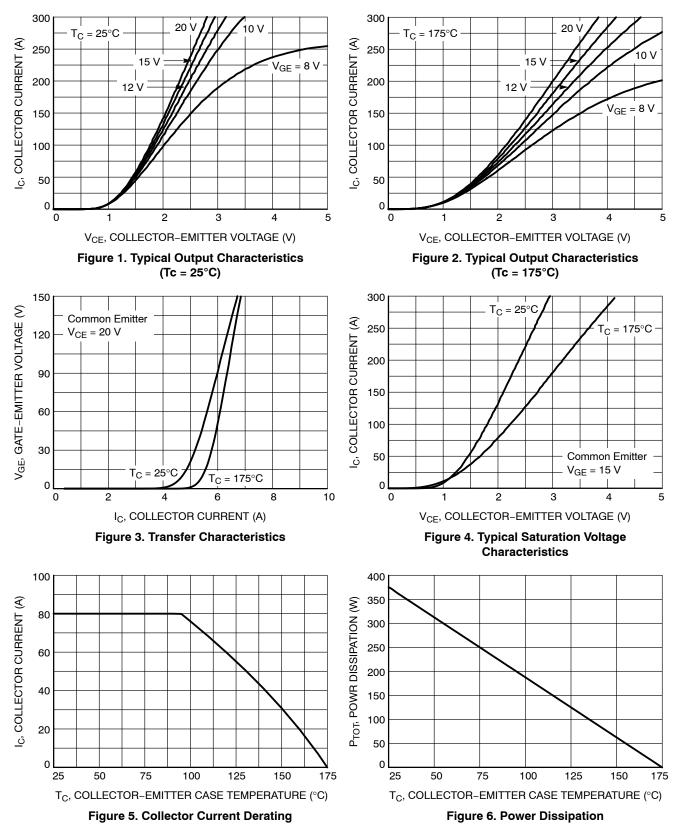
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•					
Collector-emitter breakdown voltage, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	BV <sub>CES</sub>	650	-	-	V
Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	-	0.6	-	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V	I <sub>CES</sub>	_	-	250	μΑ
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	-	±400	nA
ON CHARACTERISTICS						
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_C = 75 \text{ mA}$	V <sub>GE(th)</sub>	3.4	4.9	6.4	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A, T <sub>J</sub> = 175°C	V <sub>CE(sat)</sub>	-	1.6 2.0	2.1 -	V
DYNAMIC CHARACTERISTICS	•					
Input capacitance	$V_{CE} = 30 V,$	C <sub>ies</sub>	-	4574	-	pF
Output capacitance	V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	-	289.4	-	
Reverse transfer capacitance		C <sub>res</sub>	-	11.2	-	
Gate charge total	$V_{CE} = 400 V,$	Qg	-	139	-	nC
Gate-to-emitter charge	I <sub>C</sub> = 75 A, V <sub>GE</sub> = 15 V	Q <sub>ge</sub>	-	25	-	
Gate-to-collector charge		Q <sub>gc</sub>	-	33	-	
SWITCHING CHARACTERISTICS, INDUC	TIVE LOAD					
Turn-on delay time	$T_{\rm C} = 25^{\circ}{\rm C},$	t <sub>d(on)</sub>	-	22.4	-	ns
Rise time	V <sub>CC</sub> = 400 V, I <sub>C</sub> = 37.5 A,	t <sub>r</sub>	-	19.2	-	
Turn-off delay time	R <sub>G</sub> = 4.7 Ω, V <sub>GE</sub> = 15 V,	t <sub>d(off)</sub>	-	116.8	-	
Fall time	Inductive Load	t <sub>f</sub>	-	9.6	-	
Turn-on switching loss		E <sub>on</sub>	-	0.48	-	mJ
Turn-off switching loss		E <sub>off</sub>	-	0.24	-	
Total switching loss		E <sub>ts</sub>	-	0.72	-	
Turn-on delay time	$T_{\rm C} = 25^{\circ}{\rm C},$	t <sub>d(on)</sub>	-	24	-	ns
Rise time	$V_{CC} = 400 \text{ V}, \\ I_C = 75 \text{ A}, \\ R_G = 4.7 \Omega, \\ V_{GE} = 15 \text{ V}, \\ \end{array}$	t <sub>r</sub>	-	49.6	-	
Turn-off delay time		t <sub>d(off)</sub>	-	107.2	-	
Fall time	Inductive Load	t <sub>f</sub>	-	70.4	-	
Turn-on switching loss		Eon	-	1.68	-	mJ
Turn-off switching loss		E <sub>off</sub>	-	1.11	-	1
Total switching loss	1	E <sub>ts</sub>	-	2.79	-	

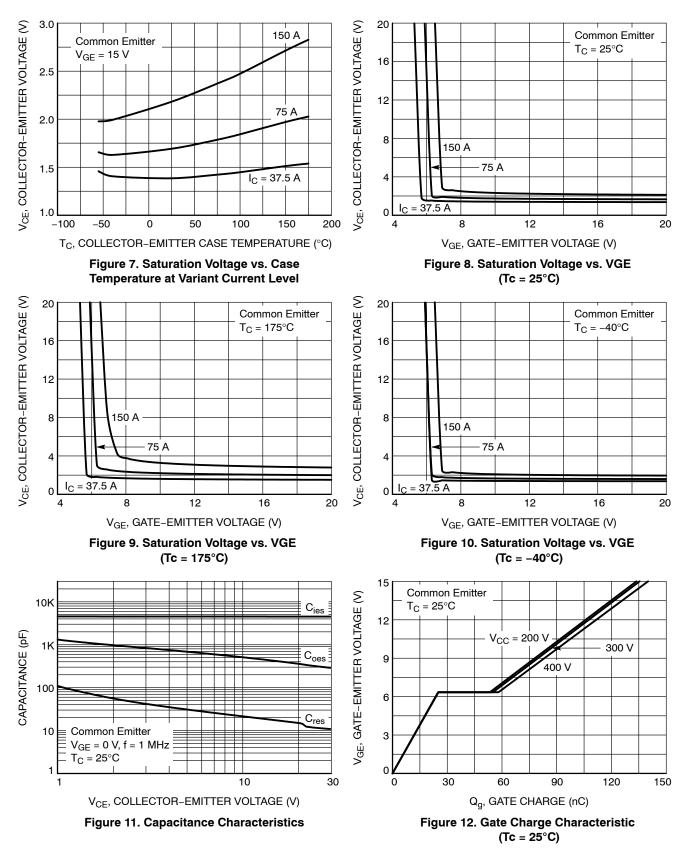
### **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

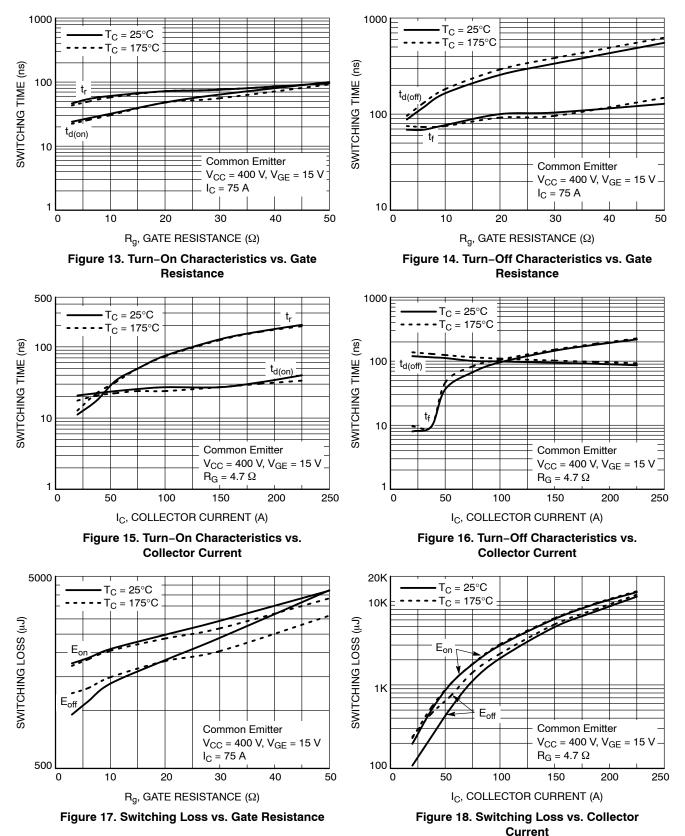
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, INDU	UCTIVE LOAD			•		
Turn-on delay time	T <sub>C</sub> = 175°C,	t <sub>d(on)</sub>	-	20.8	-	ns
Rise time	V <sub>CC</sub> = 400 V, I <sub>C</sub> = 37.5 A,	t <sub>r</sub>	-	22.4	-	
Turn-off delay time	R <sub>G</sub> = 4.7 Ω, V <sub>GE</sub> = 15 V,	t <sub>d(off)</sub>	-	130	-	
Fall time	Inductive Load	t <sub>f</sub>	-	9.6	-	
Turn-on switching loss		E <sub>on</sub>	-	0.53	-	mJ
Turn-off switching loss		E <sub>off</sub>	-	0.44	-	
Total switching loss		E <sub>ts</sub>	-	0.98	-	
Turn-on delay time	T <sub>C</sub> = 175°C,	t <sub>d(on)</sub>	-	24	-	ns
Rise time	$V_{CC} = 400 V,$ $I_{C} = 75 A,$	t <sub>r</sub>	-	49.6	-	
Turn-off delay time	R <sub>G</sub> = 4.7 Ω, V <sub>GF</sub> = 15 V,	t <sub>d(off)</sub>	-	118	-	
Fall time	Inductive Load	t <sub>f</sub>	-	78.4	-	
Turn-on switching loss		E <sub>on</sub>	-	1.76	-	mJ
Turn-off switching loss	-	E <sub>off</sub>	-	1.42	-	1
Total switching loss		E <sub>ts</sub>	-	3.19	-	1

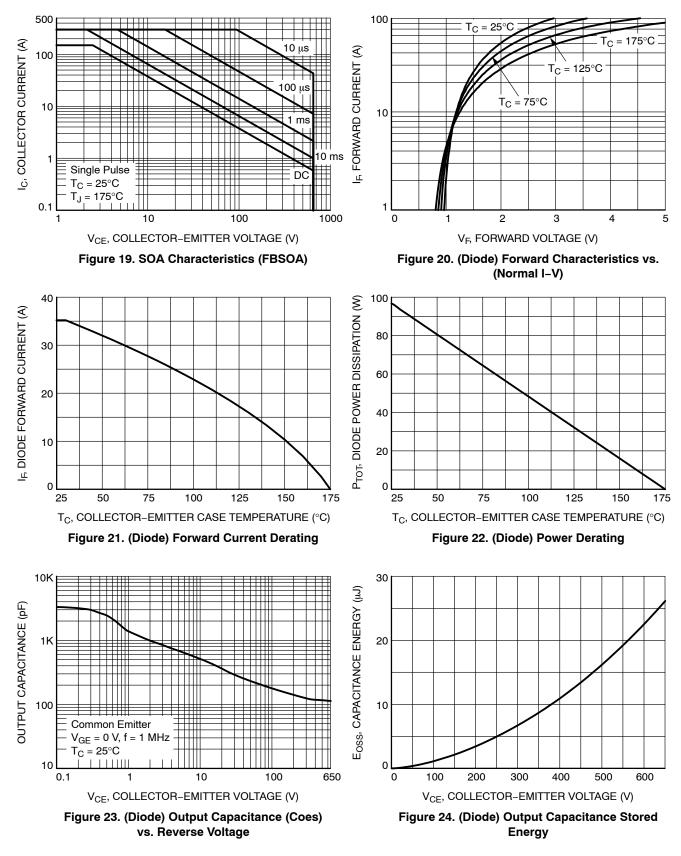
Forward Voltage	I <sub>F</sub> = 20 A	V <sub>F</sub>	-	1.45	1.75	V
	I <sub>F</sub> = 20 A, T <sub>J</sub> = 175°C		-	1.80	-	
Total Capacitance	V <sub>R</sub> = 400 V, f = 1 MHz	С	-	110	-	pF
	V <sub>R</sub> = 600 V, f = 1 MHz		-	105	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.









#### **TYPICAL CHARACTERISTICS**

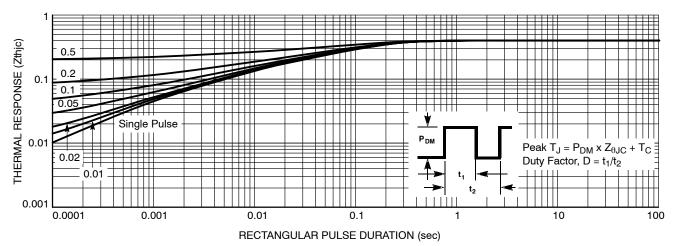


Figure 25. Transient Thermal Impedance of IGBT

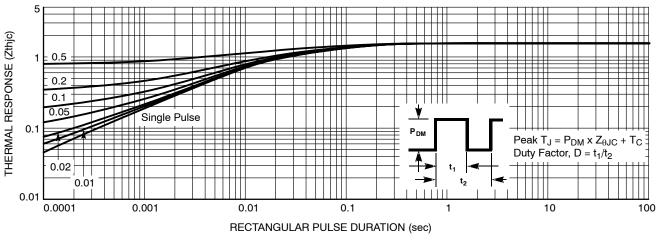
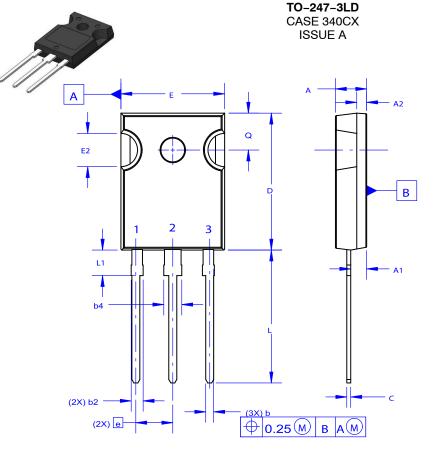


Figure 26. Transient Thermal Impedance of Diode





NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

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## GENERIC **MARKING DIAGRAM\*** Х



XXXXX	= Specific Device Code
Α	= Assembly Location

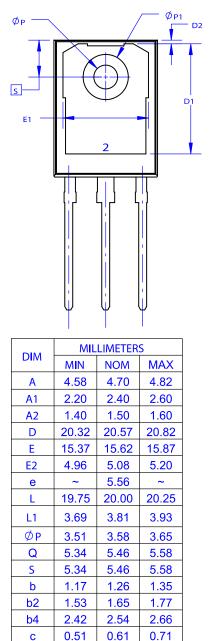
- = Assembly Location
- = Year
- ww = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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DATE 06 JUL 2020



D1

D2

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